

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph located at page 4, lines 6 through 11 with the following amended paragraph marked up to show changes made relative to the immediate prior version:

Layer 20 defines openings to pass solder columns 25. Solder columns 25 may be fabricated using currently- or hereafter-known systems, and may be coupled to electrical contacts (not shown) of substrate 10 and to electrical contacts (not shown) of interposer 30. Interposer 30 may comprise a low-CTE material. Interposer 30 comprises ceramic or silicon according to some embodiments. Interposer 30 may define a plurality of vias 32 coupled to respective ones of solder columns 25.